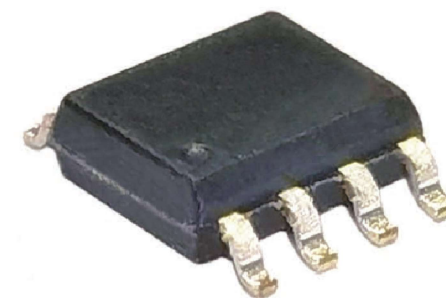


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	-	-	1.75
A1	0.10	0.15	0.20
A2	1.35	1.45	1.55
b	0.39	-	0.47
b1	0.38	0.41	0.43
c	0.20	-	0.25
c1	0.19	0.20	0.21
D	4.78	4.88	4.98
Df	4.93	-	5.33
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.27BSC		
L	0.51	0.66	0.81
L1	0.95	1.05	1.15
$\theta$	0	-	8°
f	0.05	-	0.20

Note:

1. All dimension are in mm.
2. Dim D & E1 does not include plastic flash;  
Df includes plastic flash(f);  
Flash: Plastic residual around body edge after  
dejunk/singulation.
3. Dim b does not include dambar protrusion/intrusion.
4. Plating thickness 0.007mm-0.020mm



拟制		复审	
审核		会签	
		标准化	
		批准	
制图		批准	
幅面: A4		比例: 1:1	

更改标记	更改内容	签 名	日 期
<div><div><div><div></div><div></div><div></div><div></div></div><div><div><div><div></div><div></div><div></div></div><div><b>永嘉微电</b></div><div>Vinka Microelectronics</div></div></div></div><div><div>VKXHSOP8V11_POD</div><div>产品外形图名称</div></div><div><div>图 号:VKXHSOP8V11_POD</div><div><div>单 位</div><div>mm</div><div>第 1 张</div></div><div><div>版本</div><div>V1.1</div><div>共 1 张</div></div><div><div>密 级</div><div></div></div></div><div><div><div><div></div><div></div><div></div></div><div>-</div><div><div></div><div></div><div></div></div></div></div></div>			